

ABSTRACT

A leadframe for use with integrated circuit chips comprising a base metal having a plated layer of nickel
5 fully covering the base metal; a plated layer of lead-free solder on the nickel layer, selectively covering areas of the leadframe intended for attachment to other parts; a plated layer of palladium on the nickel layer, selectively covering areas of the leadframe intended for bonding wire
10 attachment, and a plated layer of silver on both the palladium and solder layers, the silver on the solder intended to dissolve completely into the solder upon heating.

15